

IEEE 1394-1995 High-Speed Serial-Bus Link-Layer Controller

FEATURES

- **Link Core**
 - Supports Provision of IEEE 1394-1995 (1394) Standard for High-Performance Serial Bus
 - Transmits and Receives Correctly Formatted 1394 Packets
 - Supports Asynchronous and Isochronous Data Transfers
 - Performs Function of 1394 Cycle Master
 - Generates and Checks 32-Bit CRC
 - Detects Lost Cycle-Start Messages
 - Contains Asynchronous, Isochronous, and General-Receive FIFOs Totaling 2K Bytes
- **Physical-Link Interface**
 - Compatible With Texas Instruments Physical Layer Devices (PHYs)
 - Supports Transfer Speeds of 100, 200, and 400 Mbits/s
 - Timing Compliant with IEEE 1394a-2000
- **Host Bus Interface**
 - Provides Chip Control With Directly Addressable Registers
 - Is Interrupt Driven to Minimize Host Polling
 - Has a Generic 32-Bit Host Bus Interface
- **General**
 - Operates From a 3.3-V Power Supply While Maintaining 5-V Tolerant Inputs
 - Manufactured With Low-Power CMOS Technology
 - 100-Pin PZT Package for 0°C to 70°C and -40°C to 85°C (I Temperature) Operation

DESCRIPTION

The TSB12LV01B is an IEEE 1394-1995 standard (from now on referred to only as 1394) high-speed serial-bus link-layer controller that allows for easy integration into an I/O subsystem. The TSB12LV01B provides a high-performance IEEE 1394-1995 interface with the capability of transferring data between the 32-bit host bus, the 1394 PHY-link interface, and external devices connected to the local bus interface. The 1394 PHY-link interface provides the connection to the 1394 physical (PHY) layer device and is supported by the link-layer controller (LLC). The LLC provides the control for transmitting and receiving 1394 packet data between the FIFO and PHY-link interface at rates of 100 Mbits/s, 200 Mbits/s, and 400 Mbits/s. The TSB12LV01B transmits and receives correctly-formatted 1394 packets and generates and inspects the 32-bit cyclic redundancy check (CRC). The TSB12LV01B is capable of being cycle master and supports reception of isochronous data on two channels. TSB12LV01B has a generic 32-bit host bus interface, which will connect to most 32-bit hosts. The LLC also provides the capability to receive status from the physical layer device and to access the physical layer control and status registers by the application software. An internal 2K-byte memory is provided that can be configured as multiple variable-size FIFOs and eliminates the need for external FIFOs. Separate FIFOs can be user configured to support general 1394 receive, asynchronous transmit, and isochronous transmit transfer operations. These functions are accomplished by appropriately sizing the general receive FIFO (GRF), asynchronous transmit FIFO (ATF), and isochronous transmit FIFO (ITF).

The TSB12LV01B is a revision of the TSB12LV01A, with feature enhancements and corrections. It is pin for pin compatible with the TSB12LV01A with the restrictions noted below. It is also software compatible with the extensions noted below.

All errata items to the TSB12LV01A have been fixed, and the following feature enhancements have been made:

- Two new internal registers have been added at CFR address 40h and 44h. The *Host Bus Control Register* at 40h and the *Mux Control Register* @44h .
- Three programmable general-purpose output pins have been added.
- Several pin changes have been made. Refer to *TSB12LV01A to TSB12LV01B Transition Document*, TI literature number SLLA081 dated May 2000.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

However, there are three restrictions that were not present in the TSB12LV01A device:

- The TSB12LV01B may only operate with a 50 MHz host-interface clock (BCLK) if the duty cycle is less than 5% away from the 50-50 point, (i.e., the duty cycle must be within 45-55% inclusive). A 40-60% duty cycle clock is acceptable for host clock frequencies at or below 47 MHz.
- The TSB12LV01B does not have bus holder cells on the PHY-link interface.
- As a result of removing the bus holder cells, the $\overline{\text{ISO}}$ pin (pin 69) was replaced with a Vcc pin on the TSB12LV01B.

This document is not intended to serve as a tutorial on 1394; users are referred to the IEEE 1394-1995 serial bus standard for detailed information regarding the 1394 high-speed serial bus.

NOTE:

This product is for high-volume applications only. For a complete datasheet or more information contact support@ti.com.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TSB12LV01BPZT	Active	Production	TQFP (PZT) 100	90 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-4-260C-72 HR	0 to 70	TSB12LV01B F711934
TSB12LV01BPZT.A	Active	Production	TQFP (PZT) 100	90 JEDEC TRAY (10+1)	Yes	NIPDAU	Level-4-260C-72 HR	0 to 70	TSB12LV01B F711934

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

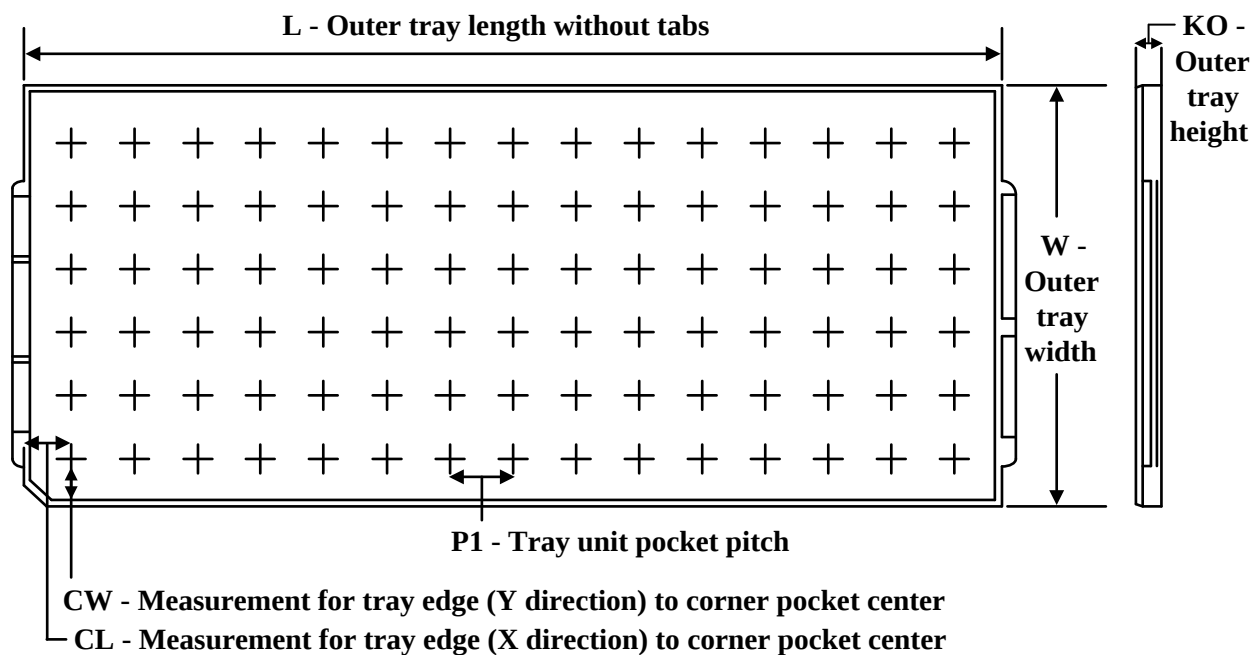
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TRAY



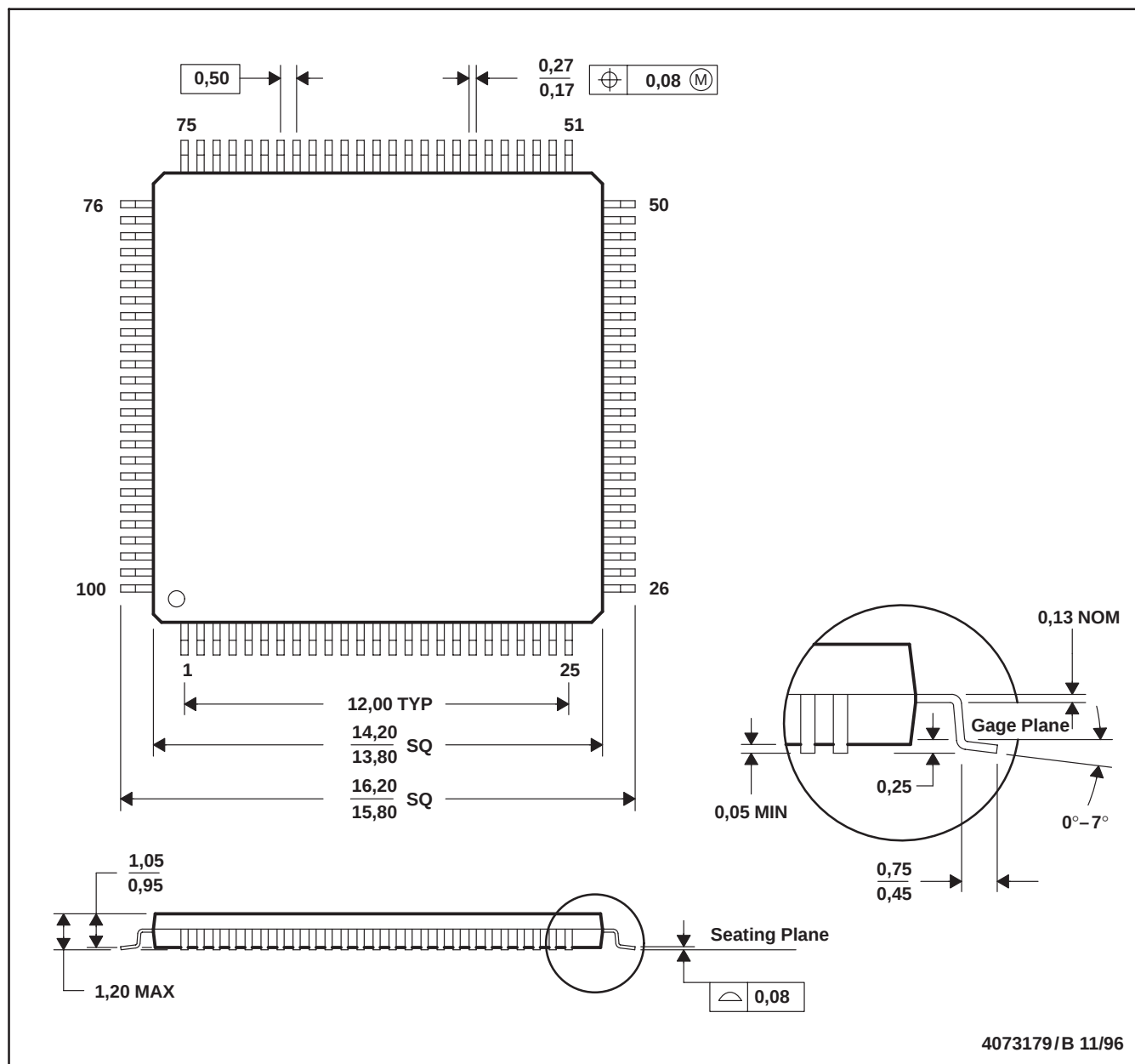
Chamfer on Tray corner indicates Pin 1 orientation of packed units.

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	Unit array matrix	Max temperature (°C)	L (mm)	W (mm)	K0 (μm)	P1 (mm)	CL (mm)	CW (mm)
TSB12LV01BPZT	PZT	TQFP	100	90	6 X 15	150	315	135.9	7620	15.4	20.3	21
TSB12LV01BPZT.A	PZT	TQFP	100	90	6 X 15	150	315	135.9	7620	15.4	20.3	21

PZT (S-PQFP-G100)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated